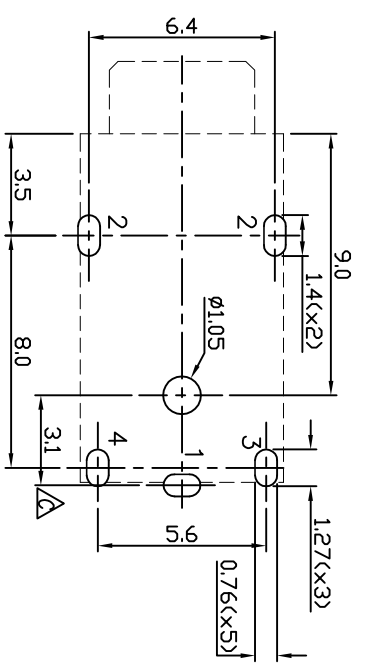
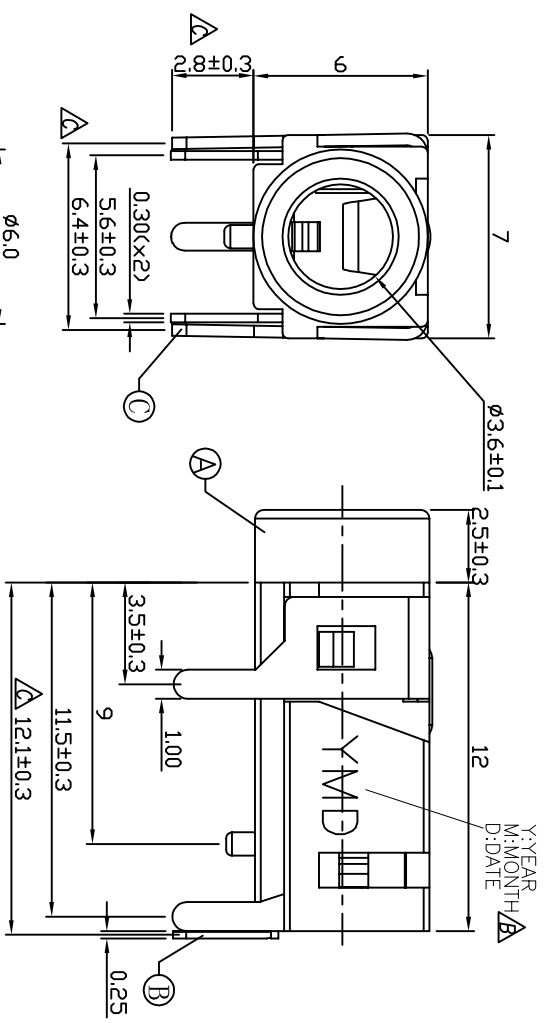
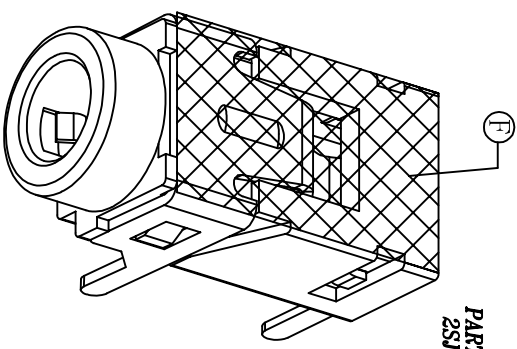


REV	ECN NO	OR DESCRIPTION	REVISED	DATE
A	PDR RELEASE	IV-C	2016.05.19	
B	ECN NO: L1720035	EVEN	2018.04.17	
C	ECN NO: L202005-001	IV-C	2020.06.15	

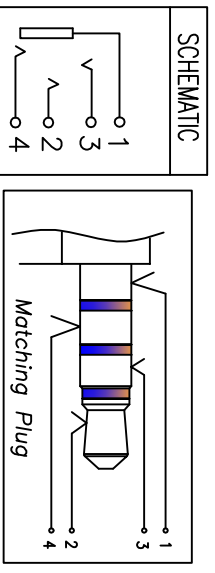
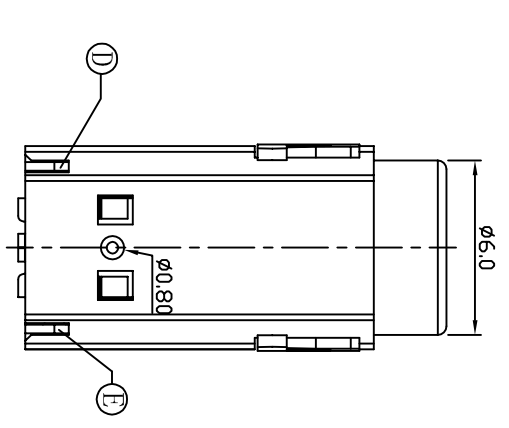
- SPECIFICATIONS:
1. TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 2. GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: G.P. PASS
 3. PACKAGE: SEE "2SJ1520-008111H" PACKAGE.
 4. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 5. OTHER GENERAL SPEC. TO REFER "2SJ1520-008111H SPEC"



T:1.6 Dimensions of PC board holes
Tolerance : ±0.05(Printed-top view)



- SUFFIX: HALOGEN
- PACKAGE 1: TAPE & REEL
- HOUSING COLOR 1: BLACK
- CONTACT PLATING 1: Ag



F	MYLAR	1	YELLOW
E	RING SPRING	1	Ag
D	RING SPRING	1	Ag
C	TIP SPRING	1	Ag
B	EARTH SPRING	1	Ag
A	HOUSING	1	BLACK

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

UNLESS OTHERWISE SPECIFIED TOLERANCES	TITLE	Ø3.5mm PHONE JACK
DECIMALS: .1	DWN	IN-C 2020.06.15
ANGLES: ±2°	CHKD	IN-C 2020.06.15
X.XX : ±0.3	APVD	IN-C 2020.06.15
X.XX : ±0.2	SIZE: A3 SHEET: 1 OF 1 REV: C	

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